bonding the first sheet to the second sheet with the modification layer therebetween, wherein the bonding surface of the first sheet contacts the bonding surface of the modification layer;

wherein the modification layer is a polymerized amorphous organosilicon and has a thickness in the range of 5 nm to 10 microns.

10. The method of claim 9, the surface energy of the modification layer bonding surface being increased by exposure to nitrogen, oxygen, hydrogen, carbon dioxide gas or a combination thereof.

11. The method of claim 9 or claim 10, the modification layer is formed by deposition of an organosilane monomer selected from the group consisting of phenylsilicon, methylphenylsilicon, diphenylsilicon, methlydiphenylsilicon and triphenylsilicon.

12. The method of claim 9 or 10, the organosilane monomer comprising a formula $(R_1)_xSi(R_2)_y$, wherein R_1 is an aryl, alkyl, alkynyl and /or alkenyl and x is 1, 2 or 3, R_2 is hydrogen, halogen, an aryl, alkyl, alkynyl and /or alkenyl, or a combination thereof and y is 1, 2 or 3, wherein R_1 and R_2 are not oxygen.

13. The method of claim 12, R_1 or R_2 being an aryl, phenyl, tolyl, xylyl, naphthyl or a combination thereof.

14. The method of claim 12, R_2 being hydrogen, methyl or a combination thereof.

15. The method of claim 12, R_1 or R_2 being an aryl.

16. The method of claim 12, R_1 or R_2 being a di-aryl.

17. The method of claim 12, the organosilane monomer being selected from the group consisting of phenylsilane, methylphenylsilane, diphenylsilane, methlydiphenylsilane and triphenylsilane.

18. The method of any one of claims 9-17, the first sheet being glass comprising a thickness of 300 microns or less and the second sheet being glass comprising a thickness of 300 microns or greater.